**STATION for Ni(P) plating process:**

REAGENTS:

20% Sulfuric acid preclean

PdSO4 in 5% Sulfuric acid seed solution

EPITHAS ANP – 1012 as plating chemistry for Ni(P)

(contains proprietary amounts of nickel sulfate, complexing agent, sodium hypophosphite reducing agent, pH buffer, and solution stabilizer)

For questions, please contact:

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